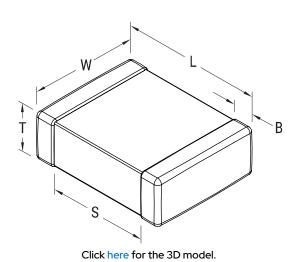




SMD Comm X8G HT150C, Ceramic, 0.33 uF, 1%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	190 mg
Shelf Life	78 Weeks
MSL	1

Dimensions		
Chip Size	2220	
L	5.7mm +/-0.4mm	
W	5mm +/-0.4mm	
Т	1.7mm +/-0.15mm	
S	3.5mm MIN	
В	0.6mm +/-0.35mm	

Packaging Specifications	
В	0.6mm +/-0.35mm
S	3.5mm MIN
Т	1.7mm +/-0.15mm
W	5mm +/-0.4mm

Specifications		
Capacitance	0.33 uF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	1%	
Voltage DC	100 VDC	
Dielectric Withstanding Voltage	250 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	3.0303 GOhms	

Packaging	T&R, 330mm, Plastic Tape	Applied (TCC)
Packaging Quantity 4	4000	Dissipation Factor
		Aging Rate

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